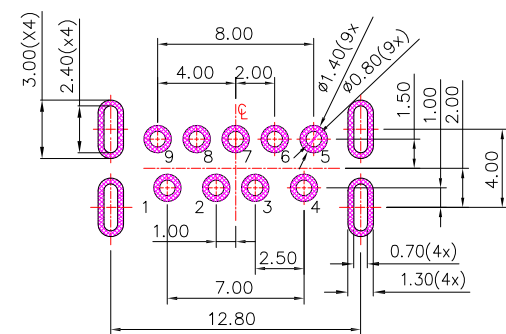
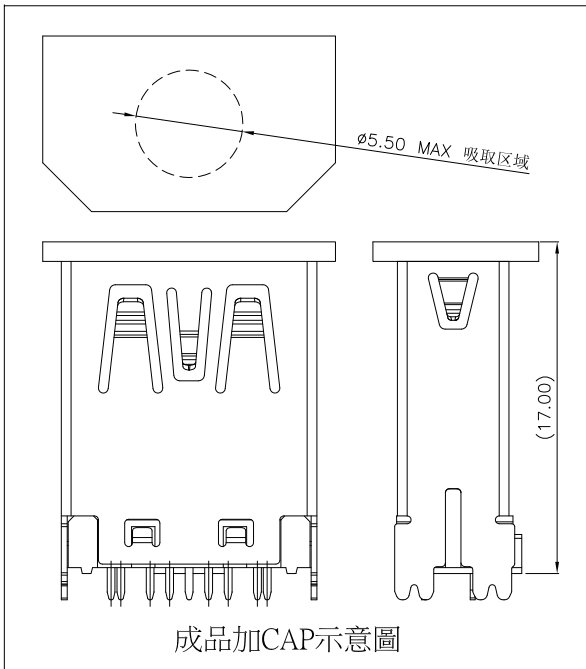
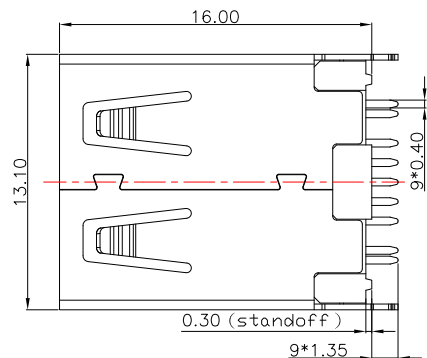




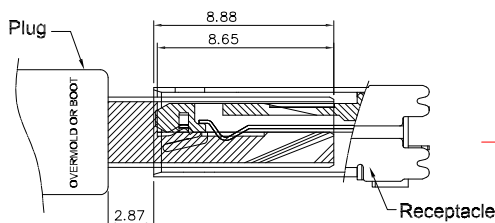
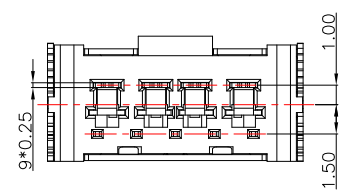
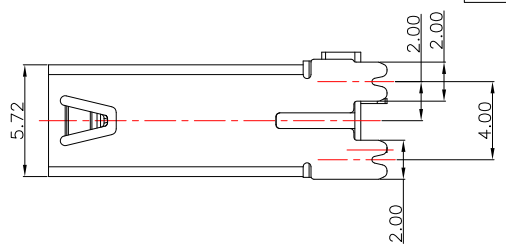
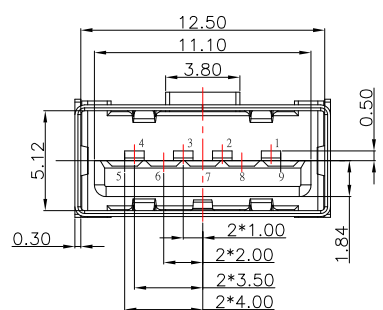
SUA-110V9-30x-S410

鍍層厚度:

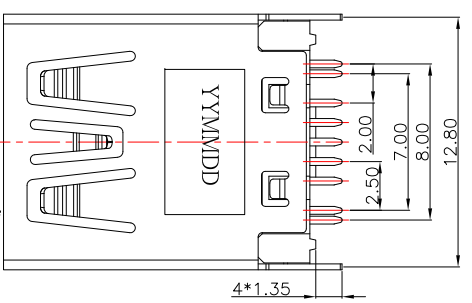
Blank	: 1u"
2	: 15u"
3	: 30u"



RECOMMENDED PCB LAYOUT



Mated Condition



Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

NOTE:

- 1.MATERIAL:
 - 1.1 Housing: LCP
 - 1.2 Contact: Phosphor Bronze
 - 1.3 Shell: SUS
- 2.Finish:
 - 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
 - 2.2 Shell: Nickel under Plated surface layer

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:	Up to 5 ±0.2	3RD. ANGEL'S	UNITS	MM
	Above 5 - 15 ±0.3			
	Above 15 - 30 ±0.4			
	Above 30 - 50 ±0.5			
	Angle ±0.3			

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	09/14/22			
CHECKED BY:	DATE	FINISH	MODLE	USB 3.0 AF 180度 H16.00 DIP 端子腳長1.35
Jacky Chen	09/14/22			
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110V9-30x-S410
Tony Kao	09/14/22	1 : 1	PART NO.	SUA-110V9-30x-S410
		SHEET NO.	1 of 1	

ITEM NO.	DESCRIPTION	DRAWN	DATE